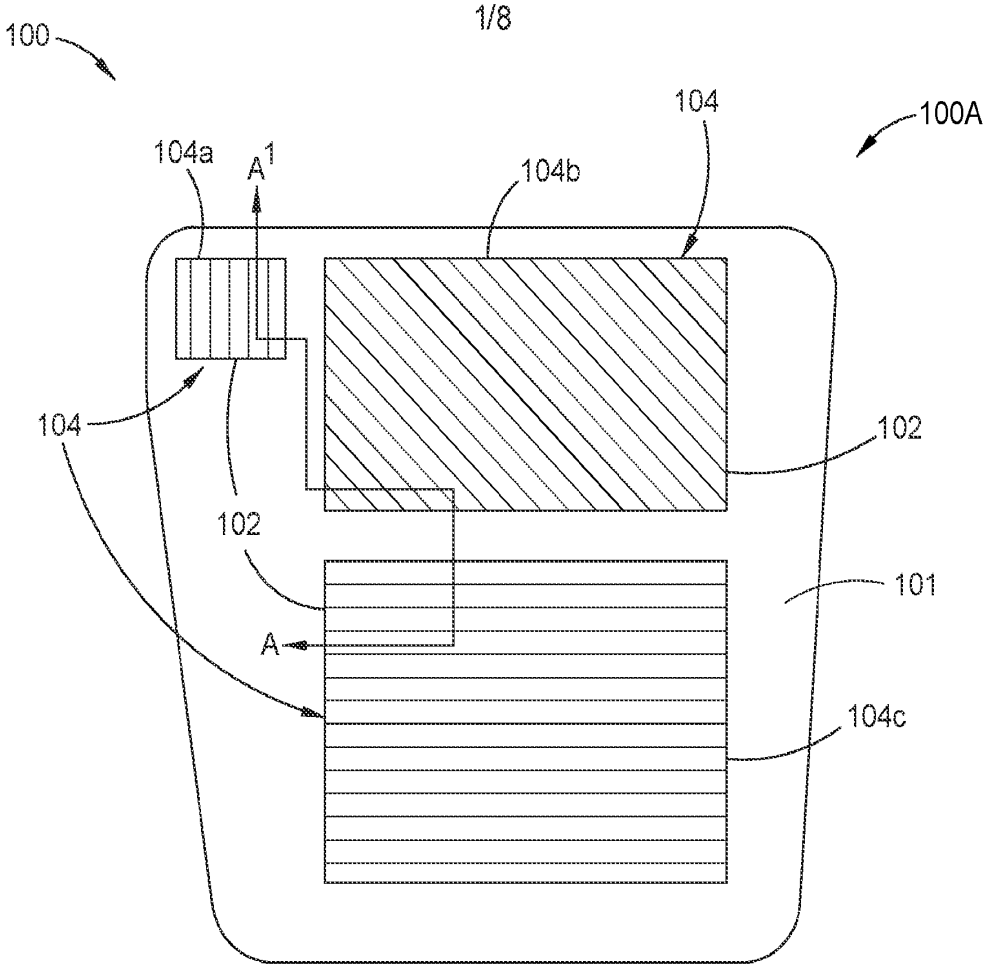

100
100A
104
104a
A1
104b
104
102
102
101
A
104c

FIG. 1A

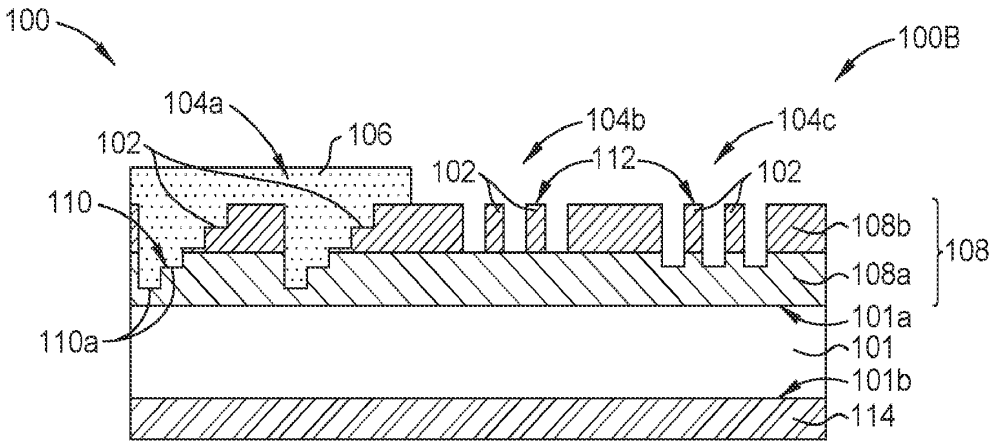

100
100B
104a
106
104b
104c
102
102
112
102
110
108b
108
108a
101a
110a
101
101b
114

FIG. 1B

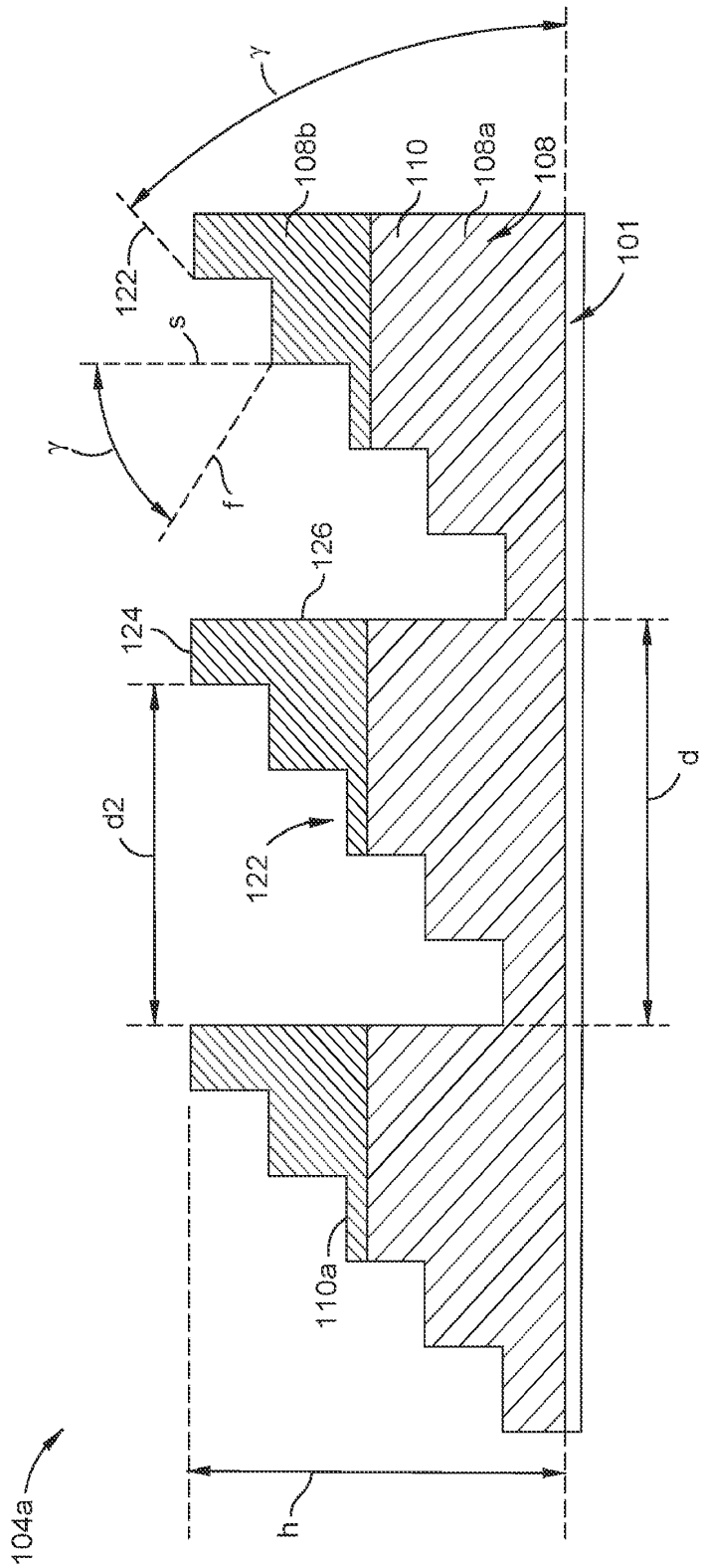


FIG. 1C

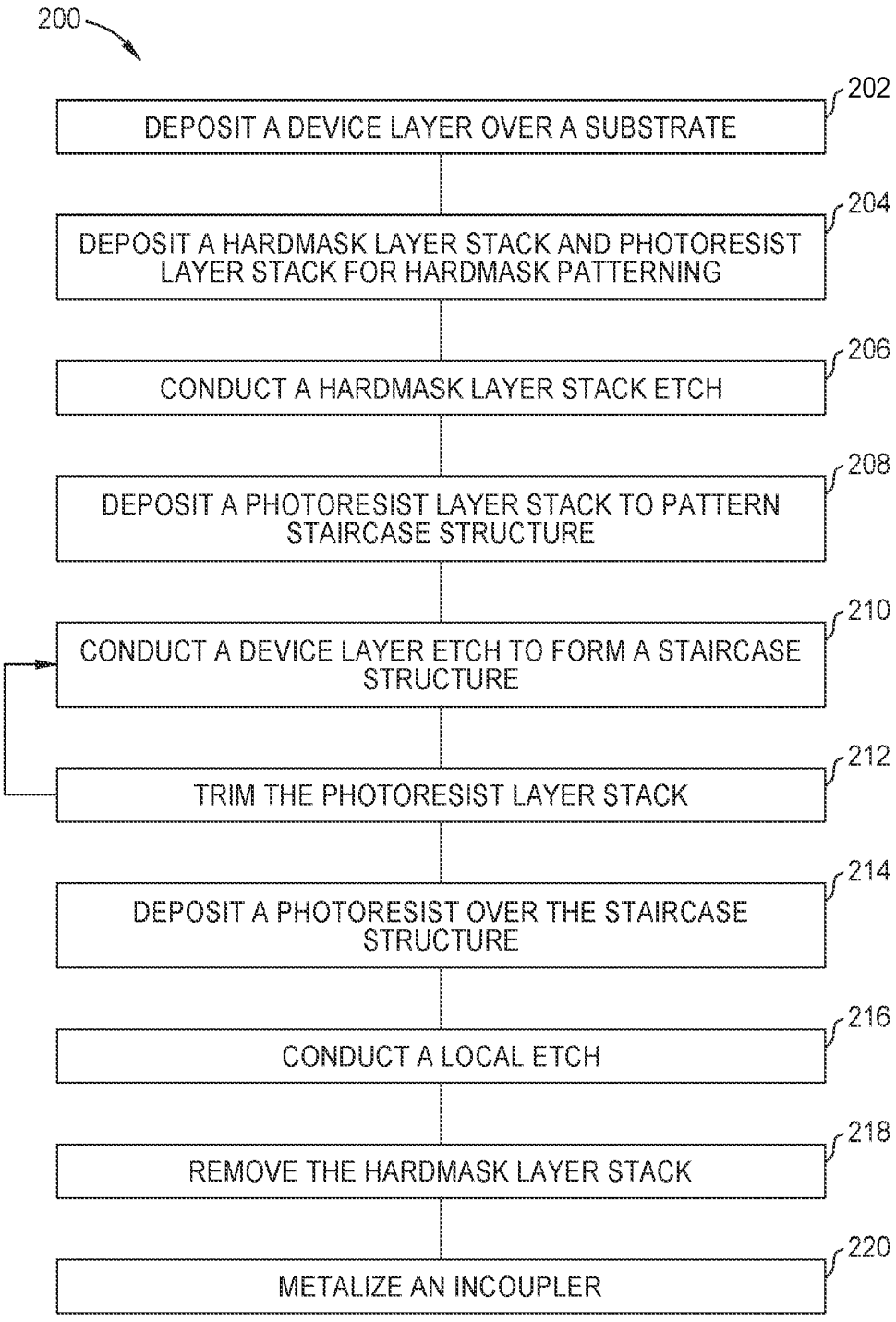

200
DEPOSIT A DEVICE LAYER OVER A SUBSTRATE
202
DEPOSIT A HARDMASK LAYER STACK AND PHOTORESIST LAYER STACK FOR HARDMASK PATTERNING
204
CONDUCT A HARDMASK LAYER STACK ETCH
206
DEPOSIT A PHOTORESIST LAYER STACK TO PATTERN STAIRCASE STRUCTURE
208
CONDUCT A DEVICE LAYER ETCH TO FORM A STAIRCASE STRUCTURE
210
TRIM THE PHOTORESIST LAYER STACK
212
DEPOSIT A PHOTORESIST OVER THE STAIRCASE STRUCTURE
214
CONDUCT A LOCAL ETCH
216
REMOVE THE HARDMASK LAYER STACK
218
METALIZE AN INCOUPLER
220

FIG. 2

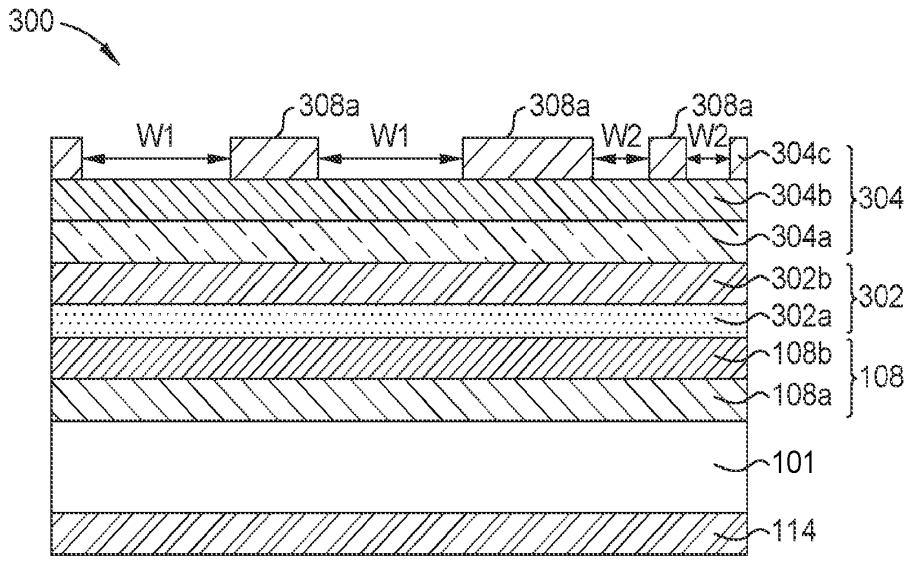

300
308a
308a
308a
W1
W1
W2
W2
304c
304b
304
304a
302b
302
302a
108b
108
108a
101
114

FIG. 3A

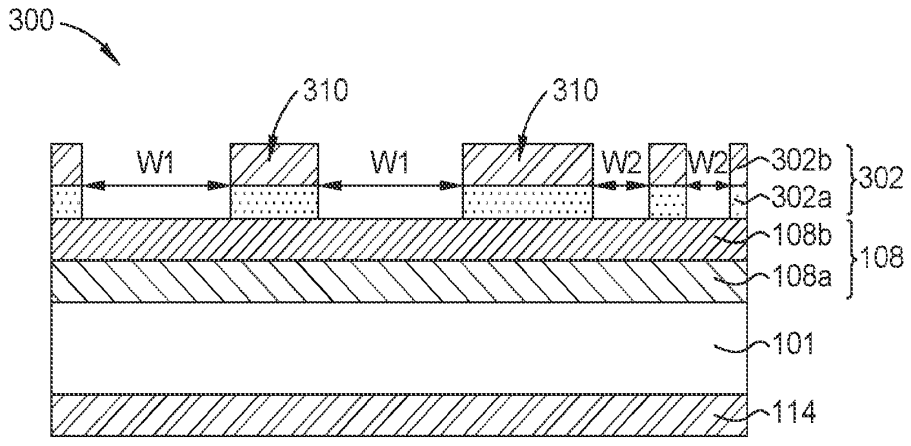

300
310
310
W1
W1
W2
W2
302b
302
302a
108b
108
108a
101
114

FIG. 3B

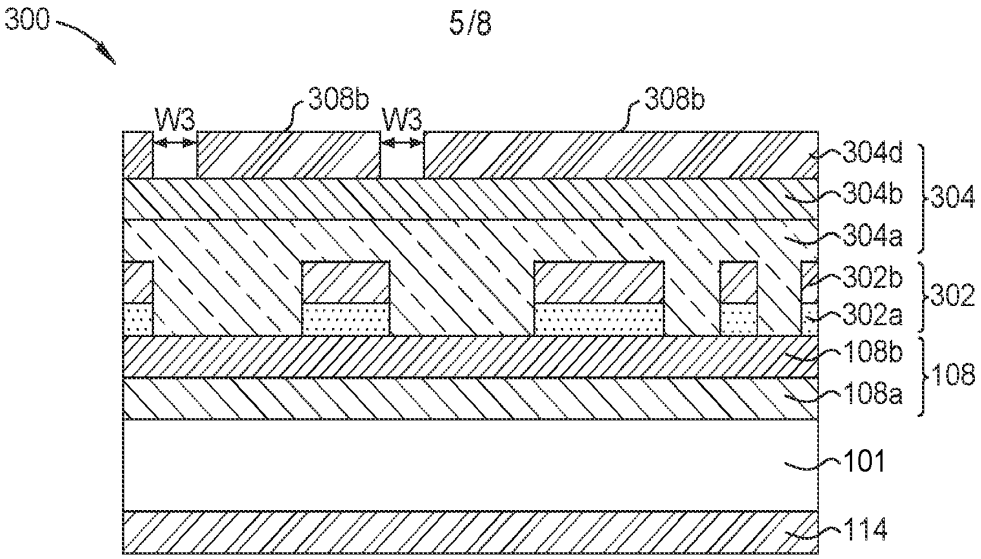


FIG. 3C

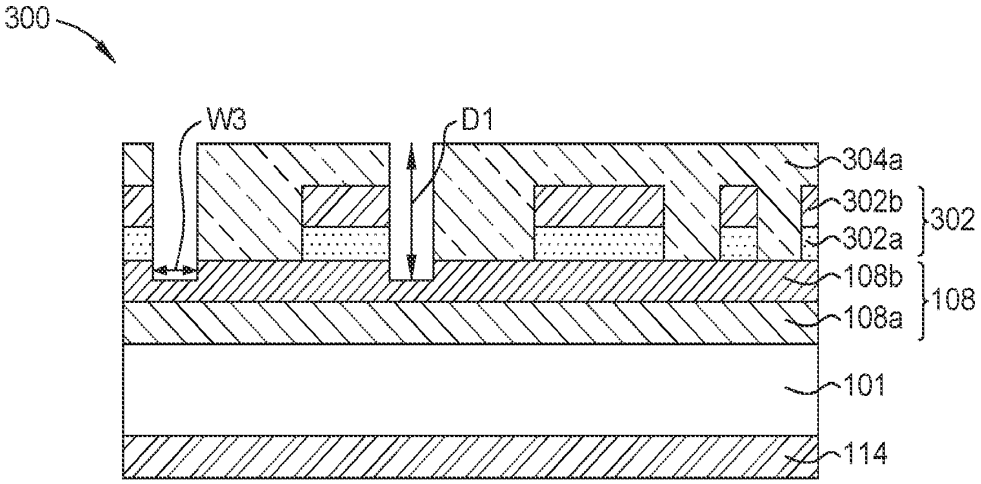


FIG. 3D

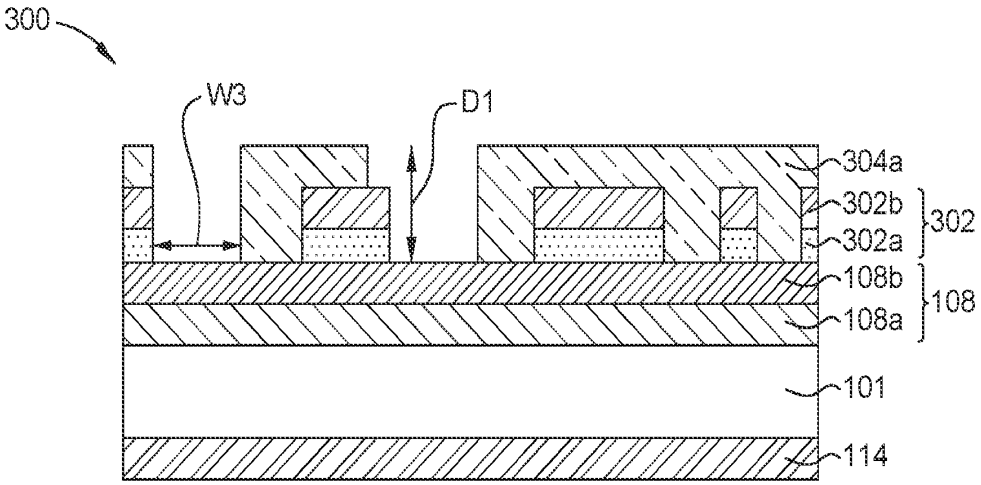


FIG. 3E

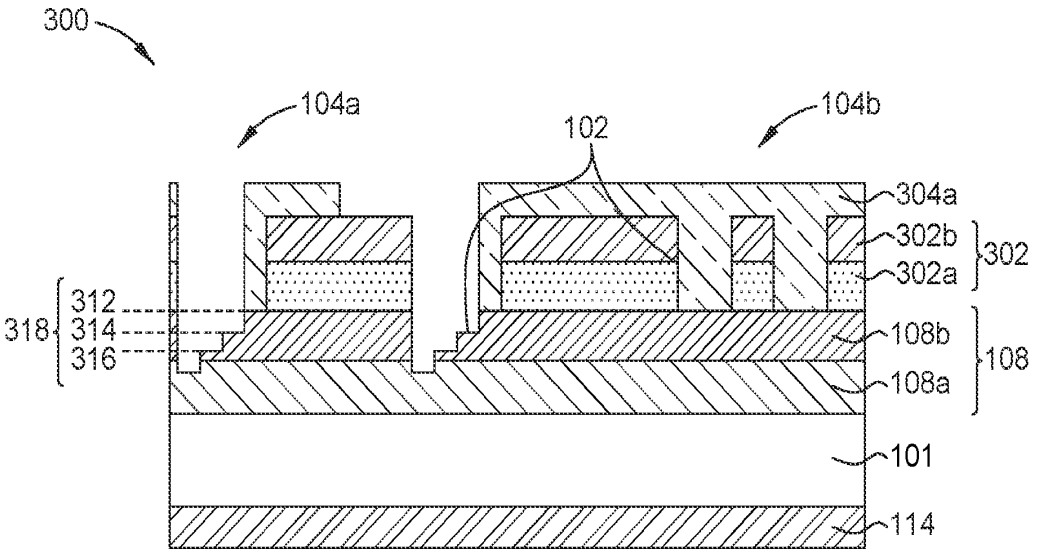

300
104a
102
104b
304a
302b
302a
302
318
312
314
316
108b
108a
108
101
114

FIG. 3F

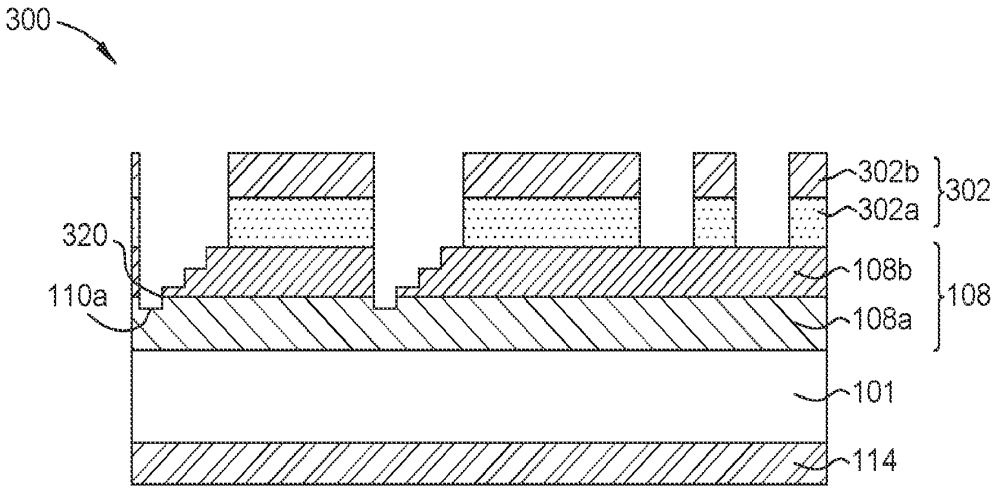

300
302b
302a
302
320
110a
108b
108a
108
101
114

FIG. 3G

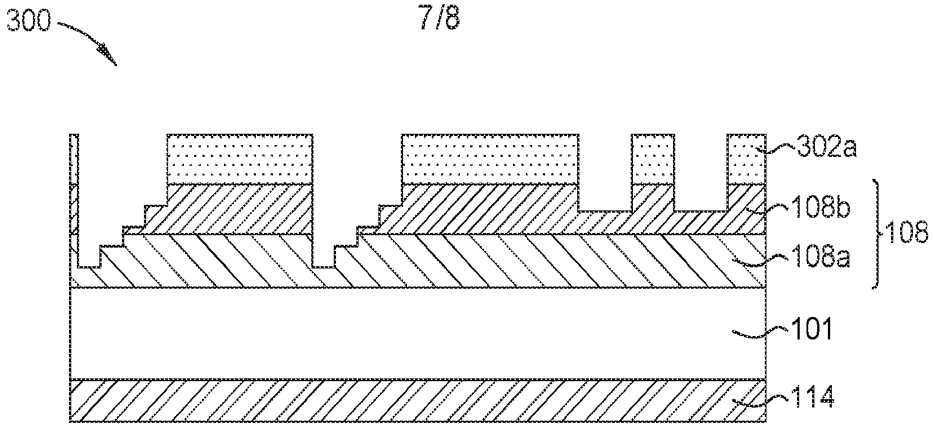


FIG. 3H

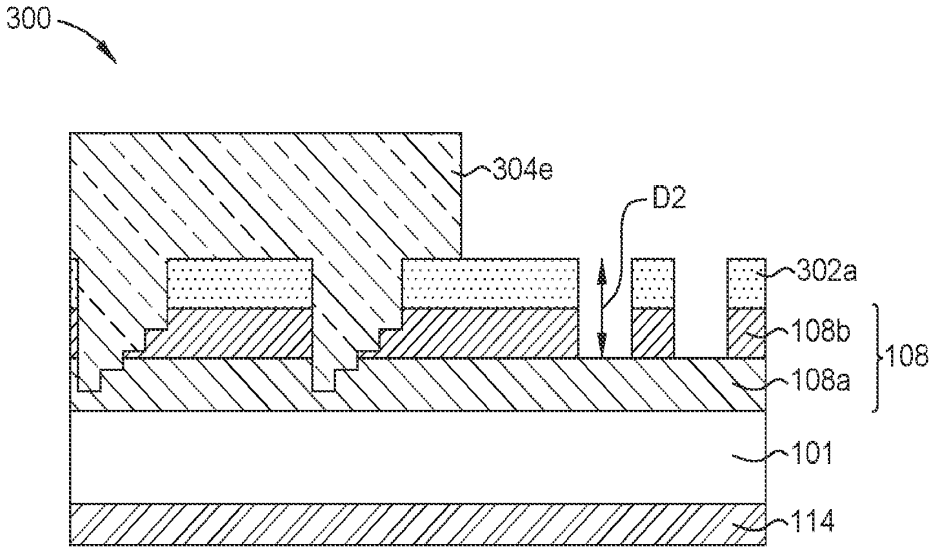


FIG. 3I

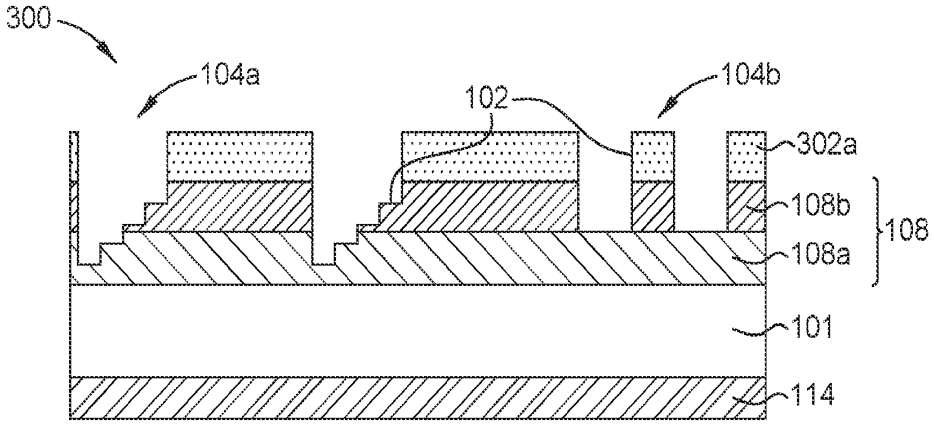


FIG. 3J

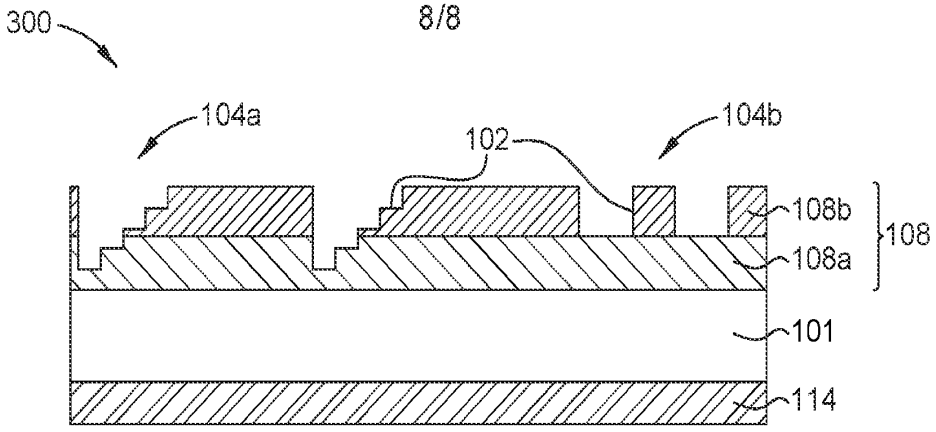


FIG. 3K

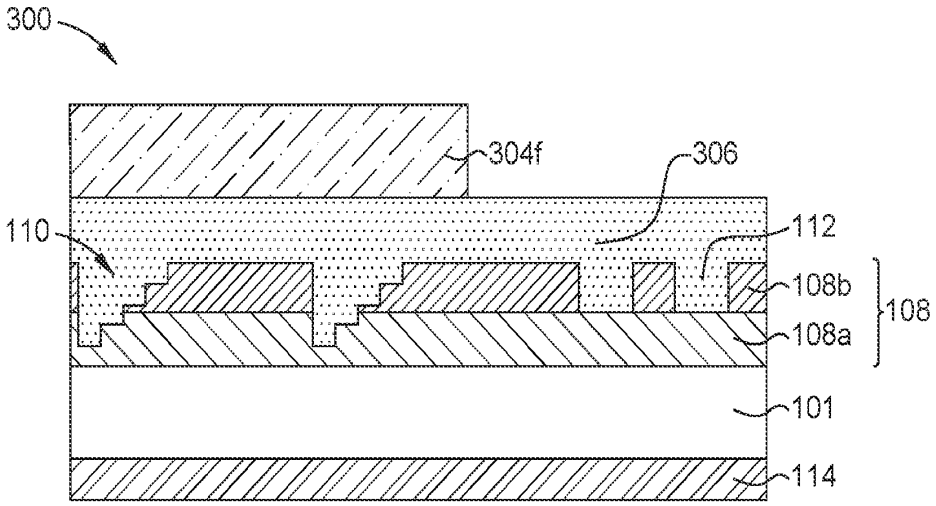


FIG. 3L

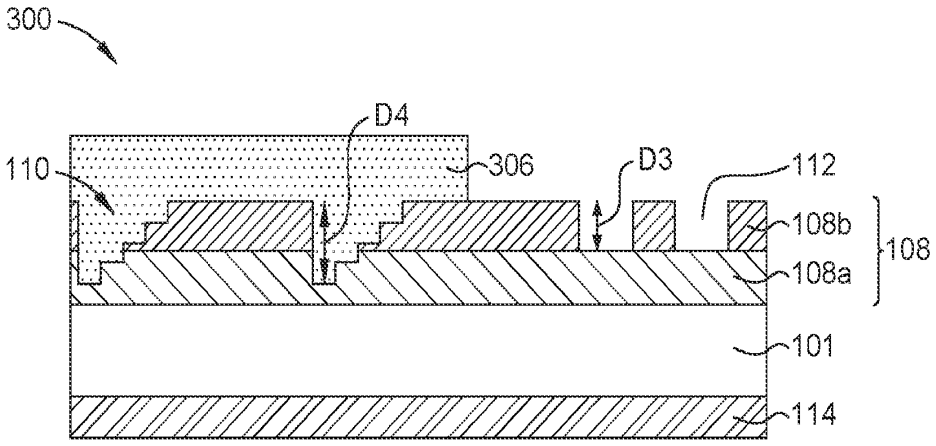


FIG. 3M